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DIALOG(R)File 347:JAPIO  
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FOAMING ADHESIVE COMPOSITION

PUB. NO.: 2004-043732 [JP 2004043732 A]  
PUBLISHED: February 12, 2004 (20040212)  
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#### ABSTRACT

PROBLEM TO BE SOLVED: To obtain a foaming adhesive composition, which is excellent in heat resistance before foaming treatment and can easily be peeled off from an adhering subject after foaming treatment.

SOLUTION: This composition comprises an adhesive polymer, a foaming ingredient containing a t-butyloxycarbonyl structure and a foaming initiator.

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DIALOG(R)File 351:Derwent WPI  
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016201250 \*\*Image available\*\*  
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Foamable adhesive-agent composition for tapes or films of adhesive sheets, comprises adhesive polymer, foamable component having t-butyloxy carbonyl structure, and foam initiator

Patent Assignee: 3M INNOVATIVE PROPERTIES CO (MINN )

Number of Countries: 001 Number of Patents: 001

Patent Family:

Patent No	Kind	Date	Applicat No	Kind	Date	Week
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Priority Applications (No Type Date): JP 2002205938 A 20020715

Patent Details:

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JP 2004043732	A		19	C09J-201/00	

Abstract (Basic): \*JP 2004043732\* A

NOVELTY - A foamable adhesive-agent composition comprises an adhesive polymer, a foamable component having a t-butyloxy carbonyl structure (1), and a foam initiator.

DETAILED DESCRIPTION - A foamable adhesive-agent composition

comprises an adhesive polymer, a foamable component having a t-butyloxy carbonyl structure of formula (1), and a foam initiator.

USE - For tapes or films of adhesive sheets used for temporary fixing in assembly processes of painting masking sheets, electronic components, protective films, semiconductor-wafer manufacture, and printed wiring boards.

ADVANTAGE - The foamable adhesive-agents composition has excellent heat resistance, and is easily peeled from an adherend.

pp; 19 DwgNo 0/0

Derwent Class: A81; G03

International Patent Class (Main): C09J-201/00

International Patent Class (Additional): C09J-004/00; C09J-133/06;  
C09J-163/00